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Abstract of the Disclosure

A method for the continuous selective electroplating of a
10 metallic substrate material (10) and more particularly of a
substrate material band having prestamped contact elements,
comprises the following steps:

- 15 a) the substrate material (10) is coated in
an electrophoretic coating means (14) with
an electrophoretic coating composition
selective with at least one composition
strip,
- b) the at least one composition strip is
20 removed at those parts by means of a laser
(40), which are to be electroplated,
- c) in an electroplating process a metal layer
is applied to the areas (42) deprived of
composition in at least one composition
strip using selective electroplating and
- 25 d) the at least one composition strip is then
removed.

Figure 1

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